

**IN THE CLAIMS:**

1. (Currently Amended) An LED mounting module for having LED devices which are to be mounted thereon, the LED mounting module[[,]] comprising:

a substrate including at least one insulation board made of an insulation material, and a wiring pattern disposed to cover at least part of a main surface of the insulation board; and

5 a ~~plurality of reflecting members each~~ member made of a resin material and having a reflecting hole in a position corresponding to ~~one of each~~ LED devices which ~~[[are]]~~ is to be mounted on one of main surfaces of the substrate, wherein

~~the substrate and the reflecting members are~~ member has a lower surface part of which is directly adhered to part of the wiring pattern opposing the part of the lower surface, and

10 a remainder of which is directly adhered to part of the insulation board opposing the remainder of the lower surface. ~~each other in such a state that the main surface of the substrate is in contact with one of main surfaces of the reflecting members, and~~

~~the reflecting members are each a separate unit.~~

2. (Currently Amended) The LED mounting module of Claim 1, wherein

~~the substrate includes an insulation board made of a resin material, and a wiring pattern on one of main surfaces of the insulation board, and~~

5 ~~[[the]]~~ a resin material forming the insulation board contains a same resin as the resin material forming the reflecting member.

3. (Original) The LED mounting module of Claim 1, wherein

the resin material is a thermosetting resin material principally containing an epoxy resin.

4. (Currently Amended) The LED mounting module of Claim 1, wherein

the wiring pattern is a surface pattern on which each LED device is to be mounted, and

the surface pattern excluding an area corresponding to the reflecting hole is entirely covered with the reflecting member.

~~the resin material is a thermoplastic resin material principally containing a resin selected from a group consisting of a polyphthalamide resin, a liquid crystal polymer, a polyphenylene sulfide resin, and a polybutylene terephthalate resin.~~

5. (Currently Amended) The LED mounting module of Claim [[1]] 4, wherein

the wiring pattern has another pattern being not formed on the main surface of the insulation board, and

a via hole electrically connecting the other pattern and the surface pattern is formed within the insulation board in an area corresponding to the lower surface of the reflecting member.

~~the resin material contains one or more fillers to improve reflection efficiency.~~

6.-27. (Cancelled)